

Printed Circuit Boards

DESIGN, FABRICATION,
AND ASSEMBLY

- ✓ High density interconnects
- ✓ CAD/CAM techniques
- ✓ Laminates
- ✓ Soldering

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Contents

1. Basics of Printed Circuit Boards

1

- 1.1 Connectivity in Electronic Equipment 1
 - 1.1.1 *Advantages of Printed Circuit Boards* 1
- 1.2 Evolution of Printed Circuit Boards 2
- 1.3 Components of a Printed Circuit Board 4
- 1.4 Classification of Printed Circuit Boards 5
 - 1.4.1 *Single-sided Printed Circuit Boards* 5
 - 1.4.2 *Double-sided Printed Circuit Boards* 6
 - 1.4.3 *Multi-layer Boards* 7
 - 1.4.4 *Rigid and Flexible Printed Circuit Boards* 9
- 1.5 Manufacturing of Basic Printed Circuit Boards 10
 - 1.5.1 *Single-sided Boards* 10
 - 1.5.2 *Double-sided Plated Through-holes* 14
 - 1.5.3 *Multi-layer Boards* 16
 - 1.5.4 *Flexible Boards* 16
- 1.6 Challenges in Modern PCB Design and Manufacture 17
- 1.7 Major Market Drivers for the PCB Industry 19
- 1.8 PCBs with Embedded Components 21
- 1.9 Standards on Printed Circuit Boards 23
- 1.10 Useful Standards 24

- 2.1 Basics of Electronic Components 25
 - 2.1.1 *Active vs Passive Components* 25
 - 2.1.2 *Discrete vs Integrated Circuits* 26
 - 2.1.3 *Component Leads* 26
 - 2.1.4 *Polarity in Components* 27
 - 2.1.5 *Component Symbols* 28
- 2.2 Resistors 29
 - 2.2.1 *Types of Resistors* 29
 - 2.2.2 *Packages* 31
 - 2.2.3 *Characteristics* 32
- 2.3 Variable Resistors or Potentiometers 35
- 2.4 Light-dependent Resistors (LDRs) 37
- 2.5 Thermistors 37
- 2.6 Capacitors 37
 - 2.6.1 *Types of Capacitors* 40
 - 2.6.2 *Packages* 42
 - 2.6.3 *Performance of Capacitors* 42
- 2.7 Variable Capacitors 44
- 2.8 Inductors 45
- 2.9 Diodes 48
- 2.10 Special Types of Diodes 50
 - 2.10.1 *Zener Diode* 51
 - 2.10.2 *Varactor Diode* 51
 - 2.10.3 *Varistor* 51
 - 2.10.4 *Light Emitting Diodes (LED)* 52
 - 2.10.5 *Photodiode* 53
 - 2.10.6 *Tunnel Diode (TD)* 53
- 2.11 Transistors 54
 - 2.11.1 *Bipolar Transistors* 54
 - 2.11.2 *Power Transistors* 58
 - 2.11.3 *Darlington Transistors* 58
 - 2.11.4 *Field-effect Transistors* 59
 - 2.11.5 *Insulated Gate Bipolar Transistor (IGBT)* 62
 - 2.11.6 *Transistor Type Numbers* 63
- 2.12 Thyristors 64
- 2.13 Integrated Circuits (ICs) 67
- 2.14 Linear Integrated Circuits 67
 - 2.14.1 *Operational Amplifiers (OP-AMP)* 68
 - 2.14.2 *Three-terminal Voltage Regulator* 71

2.15	Digital Integrated Circuits	71
2.15.1	Logic Circuits	72
2.16	Microprocessors	81
2.17	Semiconductor Memories	83
2.17.1	Random Access Memory	84
2.17.2	Read Only Memory	85
2.18	Microcontrollers	88
2.19	Surface Mount Devices	88
2.19.1	Surface Mount Devices	89
2.19.2	Surface Mounting Semiconductor Packages	92
2.19.3	Packaging of Passive Components as SMDs	97
2.20	Heat Sinks	97
2.21	Transformer	99
2.22	Relays	100
2.23	Connectors	101
2.24	Useful Standards	103

3. Layout Planning and Design

104

3.1	Reading Drawings and Diagrams	104
3.1.1	Block Diagram	104
3.1.2	Schematic Diagram	105
3.2	General PCB Design Considerations	108
3.2.1	Important Design Elements	109
3.2.2	Important Performance Parameters	109
3.3	Mechanical Design Considerations	110
3.3.1	Types of Boards	110
3.3.2	Board Mounting Techniques	115
3.3.3	Board Guiding and Retaining	116
3.3.4	Input/Output Terminations	117
3.3.5	Board Extraction	118
3.3.6	Testing and Servicing	118
3.3.7	Mechanical Stress	118
3.3.8	Board Thickness	118
3.3.9	Important Specifications and Standards	119
3.4	Electrical Design Considerations	119
3.4.1	Conductor Dimensions	119
3.4.2	Resistance	119
3.4.3	Capacitance Considerations	124
3.4.4	Inductance of PCB Conductors	126
3.4.5	High Electrical Stresses	126

3.5	Conductor Patterns	126
3.6	Component Placement Rules	127
3.6.1	Conductor Width and Thickness	127
3.6.2	Conductor Spacing	129
3.6.3	Conductor Shapes	130
3.6.4	Conductor Routing and Locations	131
3.6.5	Supply and Ground Conductors	132
3.7	Fabrication and Assembly Considerations	134
3.8	Environmental Factors	136
3.8.1	Thermal Considerations	136
3.8.2	Contamination	137
3.8.3	Shock and Vibration	137
3.9	Cooling Requirements and Packaging Density	139
3.9.1	Heat Sinks	139
3.9.2	Packaging Density	139
3.9.3	Package Style and Physical Attributes	140
3.10	Layout Design	142
3.10.1	Grid Systems	143
3.10.2	Layout Scale	143
3.10.3	Layout Sketch/Design	144
3.10.4	Layout Considerations	145
3.10.5	Materials and Aids	145
3.10.6	Land Requirements	146
3.10.7	Manual Layout Procedure	147
3.10.8	Layout Methodology	149
3.11	Layout Design Checklist	150
3.11.1	General Considerations	150
3.11.2	Electrical Considerations	150
3.11.3	Mechanical Considerations	151
3.12	Documentation	151
3.12.1	Documentation File	153
3.13	Useful Standards	153

4. Design Considerations for Special Circuits

155

4.1	Design Rules for Analog Circuits	155
4.1.1	Component Placement	155
4.1.2	Signal Conductors	156
4.1.3	Supply and Ground Conductors	161
4.1.4	General Rules for Design of Analog PCBs	162
4.2	Design Rules for Digital Circuits	162

- 4.2.1 *Transmission Lines* 163
- 4.2.2 *Problems in Design of PCBs for Digital Circuits* 164
- 4.3 *Design Rules for High Frequency Circuits* 169
- 4.4 *Design Rules for Fast Pulse Circuits* 171
 - 4.4.1 *Controlled Impedance Considerations* 172
- 4.5 *Design Rules for PCBs for Microwave Circuits* 174
 - 4.5.1 *Basic Definitions* 174
 - 4.5.2 *Strip Line and Microstrip Line* 176
 - 4.5.3 *Transmission Lines as Passive Components* 179
 - 4.5.4 *General Design Considerations for Microwave Circuits* 181
- 4.6 *Design Rules for Power Electronic Circuits* 182
 - 4.6.1 *Separating Power Circuits in High and Low Power Parts* 182
 - 4.6.2 *Base Material Thickness* 183
 - 4.6.3 *Copper Foil Thickness* 183
 - 4.6.4 *Conductor Width* 183
 - 4.6.5 *Resistive Drop of Voltage* 184
 - 4.6.6 *Thermal Considerations* 184
- 4.7 *High-density Interconnection Structures* 185
 - 4.7.1 *Drivers for HDI* 186
 - 4.7.2 *Advantages of HDI* 187
 - 4.7.3 *Designing for HDI* 188
- 4.8 *Electromagnetic Interference/Compatibility (EMI/EMC)* 190
- 4.9 *Useful Standards* 192

5. Artwork Generation

193

- 5.1 *What is Artwork?* 193
- 5.2 *Basic Approach to Manual Artwork* 193
 - 5.2.1 *Ink Drawing on White Card Board Sheets* 194
 - 5.2.2 *Black Taping on Transparent Base Foil* 194
 - 5.2.3 *Red and Blue Tape on Transparent Polyester Base Foil* 198
- 5.3 *General Design Guidelines for Artwork Preparation* 198
 - 5.3.1 *Conductor Orientation* 199
 - 5.3.2 *Conductor Routing* 200
 - 5.3.3 *Conductor Spacing* 204
 - 5.3.4 *Hole Diameter and Solder Pad Diameter* 205
 - 5.3.5 *The Square Land/Pad* 210
- 5.4 *Artwork Generation Guidelines* 210
 - 5.4.1 *No Conductor Zone* 210
 - 5.4.2 *Pad Centre Holes* 211
 - 5.4.3 *Conductor and Solder Pad Joints* 211

5.5	Film Master Preparation	211
5.5.1	Photographic Film	212
5.5.2	Exposure through Camera	215
5.5.3	Dark Room	216
5.5.4	Film Development	217
5.6	Automated Artwork Generation	219
5.7	Computer- Aided Design (CAD)	220
5.7.1	System Requirements	221
5.8	Basic CAD Operation	223
5.8.1	Layout Procedure	226
5.8.2	Library Manager	228
5.8.3	Component Placement	228
5.8.4	Conductor Routing	232
5.8.5	Checking	236
5.9	Design Automation	239
5.9.1	How to Judge CAD Systems?	240
5.10	Manual Versus Automation in PCB Design	241
5.11	Photoplotter	242
5.11.1	Vector Photoplotter	243
5.11.2	Raster (Laser) Plotters	243
5.11.3	Talking to Photoplotters	244
5.12	Computer-Aided Manufacturing (CAM)	245
5.13	Data Transfer Mechanisms	251
5.14	PCB Design Checklist	252
5.15	Useful Relevant Standards	254

6. Copper Clad Laminates

255

6.1	Anatomy of Laminates	255
6.1.1	Fillers (Reinforcements)	255
6.1.2	Resins	256
6.1.3	Copper Foil	257
6.2	Manufacture of Laminates	259
6.2.1	Materials	259
6.2.2	Process	260
6.3	Properties of Laminates	262
6.3.1	Electrical Properties	263
6.3.2	Dielectric Strength	263
6.3.3	Dielectric Constant	264
6.3.4	Dissipation Factor	264
6.3.5	Insulation Resistance	265

6.3.6	<i>Surface Resistivity</i>	265
6.3.7	<i>Volume Resistivity</i>	266
6.3.8	<i>Dielectric Breakdown</i>	267
6.4	<i>Types of Laminates</i>	267
6.4.1	<i>Phenolic Laminates</i>	267
6.4.2	<i>Epoxy Laminates</i>	269
6.4.3	<i>Glass Cloth Laminates</i>	269
6.4.4	<i>Prepreg Material [B-Stage]</i>	271
6.4.5	<i>PTFE (Polytetrafluoroethylene) Laminates</i>	272
6.4.6	<i>Polyester Laminates (Mylar Lamination),</i>	273
6.4.7	<i>Silicone Laminates</i>	273
6.4.8	<i>Melamine Laminates</i>	273
6.4.9	<i>Polyamide Laminates</i>	273
6.4.10	<i>Teflon Laminates</i>	273
6.4.11	<i>Mixed Dielectric Laminates</i>	273
6.5	<i>Evaluation of Laminates</i>	274
6.5.1	<i>Laminate Testing</i>	274
6.5.2	<i>Surface and Appearance</i>	274
6.5.3	<i>Water Absorption</i>	275
6.5.4	<i>Punchability and Machinability</i>	276
6.5.5	<i>Peel Strength</i>	276
6.5.6	<i>Bond Strength</i>	277
6.5.7	<i>Solder Resistance</i>	278
6.5.8	<i>Warp and Twist</i>	278
6.5.9	<i>Flexural Strength</i>	279
6.5.10	<i>Flammability</i>	279
6.5.11	<i>Glass Transition Temperature</i>	280
6.5.12	<i>Dimensional Stability</i>	280
6.5.13	<i>Copper Adhesion</i>	281
6.6	<i>Useful Standards</i>	281

7. Image Transfer Techniques

283

7.1	<i>What is Image Transfer?</i>	283
7.2	<i>Laminate Surface Preparation</i>	283
7.2.1	<i>Manual Cleaning Process</i>	284
7.2.2	<i>Mechanical Cleaning</i>	285
7.2.3	<i>Test for Cleanliness</i>	287
7.3	<i>Screen Printing</i>	287
7.3.1	<i>Screen Frame</i>	288
7.3.2	<i>Screen Cloth</i>	289

7.3.3	Screen Preparation	290
7.3.4	Squeegees	291
7.4	Pattern Transferring Techniques	292
7.4.1	Screen Stencil Method	292
7.4.2	Indirect Method [Transfer Type Screen Method]	293
7.4.3	Knife-cut or Hand-cut Film Process	293
7.4.4	Photographic Techniques	294
7.5	Printing Inks	295
7.5.1	Ultraviolet Curing Inks	295
7.6	Printing Process	296
7.6.1	Manual Screen Printing Process	296
7.6.2	Automatic or Semi-automatic Screen Printing Process	296
7.7	Photo Printing	296
7.7.1	Liquid Photo-resist (Wet Film Resist)	297
7.7.2	Dry Film Photo-resists	298
7.8	Laser Direct Imaging (LDI)	303
7.8.1	Benefits of LDI	307
7.9	Legend Printing	308
7.10	Useful Standards	309

8. Plating Processes

310

8.1	Need for Plating	310
8.2	Electroplating	313
8.2.1	The Basic Electroplating Process	313
8.2.2	Faraday's Laws of Electrolysis	314
8.2.3	Water Quality	315
8.2.4	pH of a Solution	316
8.2.5	Buffer	316
8.2.6	Anodes	317
8.2.7	Anode Bags	317
8.2.8	Pre-treatment for Electroplating	317
8.3	Plating Techniques	317
8.3.1	Immersion Plating	318
8.3.2	Electroless Plating	318
8.3.3	Electroplating	324
8.4	General Problems in Plating	334
8.5	General Plating Defects	334
8.5.1	Voids	334
8.5.2	Blow Holes	334
8.5.3	Outgassing	334

- 8.6 Special Plating Techniques 335
 - 8.6.1 Through-hole Plating 335
 - 8.6.2 Reel-to-Reel Selective Plating 335
 - 8.6.3 Brush Plating 336
 - 8.6.4 Finger Plating 336
 - 8.6.5 Conductor Metal Paste Coating 337
 - 8.6.6 Reduction Silver Spraying 338
- 8.7 Metal Distribution and Plating Thickness 338
 - 8.7.1 Analysis of Solution (Wet Chemical Analysis) 338
 - 8.7.2 Physical Tests for Solutions 339
 - 8.7.3 Testing of Electrodeposits 341
- 8.8 Considerations for Shop Floor 343
 - 8.8.1 Plating Shop Layout 344
 - 8.8.2 Equipment 345
- 8.9 Additive Processing 346
 - 8.9.1 Fully Additive Process 347
 - 8.9.2 Semi Additive Process 349
 - 8.9.3 Partially Additive Process 349
- 8.10 Solder Mask 352
 - 8.10.1 Solder Resist Classification 352
 - 8.10.2 Liquid Film Solder Mask 354
 - 8.10.3 Dry Film Solder Masking 354
 - 8.10.4 Resolution 357
 - 8.10.5 Encapsulation 357
 - 8.10.6 Surface Topography Resist Thickness 358
 - 8.10.7 Placement Assistance 358
 - 8.10.8 Reliability of Solder Mask 359
 - 8.10.9 Soldering and Cleaning 359
 - 8.10.10 Tenting of Vias 359
 - 8.10.11 Solder Mask over Bare Copper [SMOBC] 360
- 8.11 Conformal Coatings 361
 - 8.11.1 Materials for Conformal Coatings 361
 - 8.11.2 Methods of Applying Conformal Coatings 363
 - 8.11.3 Standards for Coatings 363
- 8.12 Useful Standards 363

9. Etching Techniques**365**

- 9.1 Etching Solutions and Chemistry 365
 - 9.1.1 Ferric Chloride 366
 - 9.1.2 Hydrogen Peroxide — Sulphuric Acid 368

9.1.3	<i>Chromic-Sulphuric Acid</i>	369
9.1.4	<i>Cupric Chloride</i>	369
9.1.5	<i>Ammonium Persulphate</i>	371
9.1.6	<i>Alkaline Ammoniacal /Ammonium Chloride</i>	373
9.2	<i>Etching Arrangements</i>	374
9.2.1	<i>Simple Batch Production Etching</i>	374
9.2.2	<i>Continuous Feed Etching</i>	374
9.2.3	<i>Open Loop Regeneration</i>	375
9.2.4	<i>Closed Loop Regeneration</i>	375
9.3	<i>Etching Parameters</i>	376
9.4	<i>Equipment and Techniques</i>	376
9.4.1	<i>Immersion Etching</i>	376
9.4.2	<i>Bubble Etching</i>	377
9.4.3	<i>Splash Etching</i>	377
9.4.4	<i>Spray Etching</i>	378
9.5	<i>Etching Equipment Selection</i>	379
9.6	<i>Optimizing Etchant Economy</i>	380
9.7	<i>Problems in Etching</i>	380
9.7.1	<i>Under-etching or Under-cut</i>	380
9.7.2	<i>Overhang</i>	381
9.8	<i>Facilities for Etching Area</i>	382
9.9	<i>Electrochemical Etching</i>	382
9.10	<i>Mechanical Etching</i>	382

10. Mechanical Operations

384

10.1	<i>Need for Mechanical Operations</i>	384
10.2	<i>Cutting Methods</i>	385
10.2.1	<i>Shearing</i>	385
10.2.2	<i>Sawing</i>	385
10.2.3	<i>Blanking of PCBs</i>	386
10.2.4	<i>Milling</i>	387
10.2.5	<i>Routing of PCBs</i>	387
10.3	<i>Hole Punching</i>	390
10.4	<i>Drilling</i>	391
10.4.1	<i>Drill Bit Geometry and its Importance</i>	393
10.4.2	<i>Types of Drill Bits</i>	395
10.4.3	<i>Drill Bit Inspection</i>	396
10.4.4	<i>Drill Bit Sizes</i>	397
10.4.5	<i>Tool Life and Re-grinding (Re-pointing)</i>	398
10.4.6	<i>Requirements in Drilling</i>	398

10.4.7	<i>Drill Speed, Feed and Withdrawal Rates</i>	398
10.4.8	<i>Function of Clean Holes</i>	399
10.4.9	<i>Drill Entry and Exit (Back-up) Materials</i>	400
10.4.10	<i>Use of Drill Bush/Collar</i>	401
10.4.11	<i>Drilling and Types of Laminates</i>	402
10.4.12	<i>Drilling Problems</i>	403
10.4.13	<i>Drilling Machines</i>	403
10.5	<i>Microvias</i>	406
10.5.1	<i>Photo-formed Vias</i>	406
10.5.2	<i>Plasma Etching</i>	407
10.5.3	<i>Laser-formed Vias</i>	407
10.6	<i>Use of UV Laser for Drilling PCB</i>	409
10.7	<i>Hybrid Laser Drilling Process</i>	410
10.8	<i>Useful Standards</i>	413

11. Multi-layer Boards

414

11.1	<i>What are Multi-layers?</i>	414
11.2	<i>Interconnection Techniques</i>	415
11.2.1	<i>Conventional Plated Through-hole</i>	415
11.2.2	<i>Buried Via</i>	416
11.2.3	<i>Blind Vias</i>	416
11.3	<i>Materials for Multi-layer Boards</i>	417
11.3.1	<i>Resin System</i>	417
11.3.2	<i>Reinforcement Materials</i>	417
11.3.3	<i>Prepreg</i>	418
11.3.4	<i>Copper Foil</i>	418
11.4	<i>Design Features of Multi-layer Boards</i>	418
11.4.1	<i>Mechanical Design Considerations</i>	419
11.4.2	<i>Electrical Design Considerations</i>	420
11.5	<i>Fabrication Process for Multi-layer Boards</i>	421
11.5.1	<i>General Process</i>	421
11.5.2	<i>Lamination</i>	422
11.5.3	<i>Post-lamination Process</i>	423
11.5.4	<i>Multi-layer Drilling</i>	424
11.5.5	<i>Schematic Key for Multi-layer Built-ups</i>	424
11.6	<i>Useful Standards</i>	425

12. Flexible Printed Circuit Boards

427

12.1	<i>What are Flexible Printed Circuit Boards?</i>	427
12.2	<i>Construction of Flexible Printed Circuit Boards</i>	428

12.2.1	<i>Films — Types and Their Characteristics</i>	429
12.2.2	<i>Foils</i>	433
12.2.3	<i>Adhesives</i>	436
12.3	<i>Design Considerations in Flexible Circuits</i>	440
12.3.1	<i>Difference in Design Considerations of Rigid and Flexible Circuits</i>	440
12.3.2	<i>Step-by-step Approach to Designing of a Flex Circuit</i>	444
12.3.3	<i>Designing for Flexibility and Reliability</i>	444
12.4	<i>Manufacture of Flexible Circuits</i>	446
12.5	<i>Rigid Flex Printed Circuit Boards</i>	448
12.6	<i>Terminations</i>	449
12.7	<i>Advantages of Flexible Circuits</i>	451
12.8	<i>Special Applications of Flexible Circuits</i>	451
12.9	<i>Useful Standards</i>	452

13. Soldering, Assembly and Re-working Techniques

453

13.1	<i>What is Soldering?</i>	453
13.2	<i>Theory of Soldering</i>	454
13.2.1	<i>The Wetting Action</i>	455
13.2.2	<i>Surface Tension</i>	455
13.2.3	<i>Creation of an Inter-metallic Compound</i>	455
13.2.4	<i>The Wetting Angle</i>	457
13.3	<i>Soldering Variables</i>	457
13.3.1	<i>Temperature and Time Taken for Soldering</i>	457
13.3.2	<i>Tarnish-free Surface</i>	457
13.3.3	<i>Application of Right Flux and Proper Solder</i>	458
13.4	<i>Soldering Material</i>	458
13.4.1	<i>Solder</i>	458
13.4.2	<i>Flux</i>	462
13.5	<i>Soldering and Brazing</i>	466
13.5.1	<i>Solders for Hard Soldering/Brazing</i>	466
13.6	<i>Soldering Tools</i>	466
13.6.1	<i>Soldering Iron</i>	466
13.7	<i>Other Hand Soldering Tools</i>	472
13.7.1	<i>Cutters</i>	473
13.7.2	<i>Pliers</i>	474
13.7.3	<i>Strippers</i>	475
13.7.4	<i>Bending Tools</i>	476
13.7.5	<i>Heat Sinks</i>	476
13.7.6	<i>General Cleaning Tools</i>	476
13.8	<i>Hand Soldering</i>	477

13.8.1	<i>Hand Soldering Requirements</i>	477
13.8.2	<i>Steps in Hand Soldering</i>	478
13.8.3	<i>Soldering Leadless Capacitors</i>	480
13.9	PCB Assembly Process	481
13.9.1	<i>Leaded Through-hole Assembly</i>	482
13.9.2	<i>Surface Mount Assembly</i>	488
13.9.3	<i>Combinations of Mixed Technologies</i>	492
13.10	Solder Pastes for SMDS	494
13.10.1	<i>Requirements of Solder Pastes</i>	495
13.10.2	<i>Composition of Solder Pastes</i>	495
13.10.3	<i>Solder Paste Application</i>	496
13.10.4	<i>Handling of Solder Paste</i>	496
13.10.5	<i>Stencil Printing of Solder Paste</i>	497
13.10.6	<i>Screen Printing of Solder Paste</i>	498
13.10.7	<i>Pre-forms of Solder</i>	501
13.10.8	<i>No-clean Solder Paste</i>	501
13.11	Adhesive for Mixed Technology Assembly	501
13.11.1	<i>Requirements of Adhesive</i>	502
13.11.2	<i>Application of Adhesive</i>	502
13.12	Mass Soldering	504
13.12.1	<i>Dip Soldering</i>	504
13.12.2	<i>Drag Soldering</i>	505
13.12.3	<i>Wave Soldering</i>	505
13.12.4	<i>Reflow Soldering</i>	512
13.12.5	<i>Vapour Phase System</i>	517
13.13	Post-soldering Cleaning	519
13.13.1	<i>Types of Contamination</i>	519
13.13.2	<i>Solvents and Cleaning Methods</i>	520
13.14	Quality Control of Solder Joints	521
13.14.1	<i>Good Quality Solder Joints</i>	522
13.14.2	<i>Common Soldering Faults</i>	522
13.14.3	<i>Solder Joint Defects and their Common Causes</i>	528
13.15	Health and Safety Aspects	531
13.16	Electrostatic Discharge Control	532
13.16.1	<i>Fundamentals of ESD</i>	533
13.16.2	<i>Electrostatic Voltages Generated by Various Operations</i>	534
13.16.3	<i>Sensitivity of Various Components to ESD Voltages</i>	535
13.16.4	<i>Electrostatic Protection</i>	535
13.16.5	<i>Anti-static Workstation</i>	536
13.16.6	<i>A Proper Assembly Environment</i>	537
13.16.7	<i>Component Handling</i>	538

- 13.16.8 *Special Considerations for Handling MOS Devices* 539
- 13.16.9 *Education/Certificate for ESD Control* 541
- 13.17 *Re-work and Repair of Printed Circuit Boards* 541
 - 13.17.1 *Approaching Components for Tests* 542
 - 13.17.2 *De-soldering Techniques* 543
 - 13.17.3 *Replacement of Components* 546
- 13.18 *Repairing Surface Mounted PCBs* 549
 - 13.18.1 *Cut all Leads* 549
 - 13.18.2 *Heating Methods* 550
 - 13.18.3 *Removal and Replacement of Surface Mount Devices* 551
 - 13.18.4 *Re-work Stations* 554
- 13.19 *Useful Standards* 557

14. Quality, Reliability and Acceptability Aspects

561

- 14.1 *What is Quality Assurance?* 561
 - 14.1.1 *Classification of Defects* 562
 - 14.1.2 *Defectives* 562
 - 14.1.3 *Acceptability Quality Level (AQL)* 562
 - 14.1.4 *Quality Control Programme* 563
 - 14.1.5 *Statistical Process Control and Sampling Plan* 563
- 14.2 *Testing for Quality Control* 564
 - 14.2.1 *Characteristics for Testing for Quality Assurance* 565
 - 14.2.2 *Designing a QA Programme* 566
 - 14.2.3 *Incoming QA* 567
 - 14.2.4 *Traceability* 567
- 14.3 *Quality Control Methods* 567
 - 14.3.1 *Micro-sectioning* 568
- 14.4 *Testing of Printed Circuit Boards* 570
 - 14.4.1 *Automatic Board Testing* 571
 - 14.4.2 *Bare Board Testing (BBT)* 573
 - 14.4.3 *Testing of Assembled Boards* 579
- 14.5 *Reliability Testing* 581
 - 14.5.1 *Reliability of Printed Circuit Boards* 581
- 14.6 *Acceptability of PCBs* 584
 - 14.6.1 *Acceptance Criteria* 585
 - 14.6.2 *Inspection of Assembled PCBs* 586
 - 14.6.3 *Inspection Techniques* 587
 - 14.6.4 *Acceptability Criteria* 596
- 14.7 *Useful Standards* 607

15. Environmental Concerns in PCB Industry

611

- 15.1 Pollution Control in PCB Industry 611
 - 15.2 Polluting Agents 612
 - 15.3 Recycling of Water 613
 - 15.4 Recovery Techniques 613
 - 15.4.1 Filtration 614
 - 15.4.2 Water Use Reduction Technique 614
 - 15.4.3 Ion Exchange System 615
 - 15.4.4 Reverse Osmosis 617
 - 15.4.5 Evaporative Recovery 618
 - 15.4.6 Precipitation of Heavy Metals 619
 - 15.4.7 Electrolytic Recovery 619
 - 15.5 Air Pollution 620
 - 15.5.1 Dust 621
 - 15.5.2 Fumes 621
 - 15.5.3 Clean Environment in Assembly Rooms 622
 - 15.6 Recycling of Printed Circuit Boards 623
 - 15.6.1 Present Approach to PCB Scrap Disposal 623
 - 15.6.2 Characteristics of PCB Scrap 625
 - 15.6.3 Dis-assembly of Equipment 625
 - 15.6.4 Technologies of Recycling of PCBs 626
 - 15.7 Environmental Standards 628
 - 15.8 Safety Precautions for the Personnel 629
 - 15.9 Toxic Chemicals in PCB Fabrication 629
 - 15.10 Lead-free Soldering 630
 - 15.10.1 Substitutes for Tin/Lead Solders 632
 - 15.11 Useful Standards 633
- Glossary 635
- References 667
- Index 678